



立体成型基板用ソルダーレジスト

MD-300 Series

● 3D-MID基板の作成方法 Process flow of 3D-MID

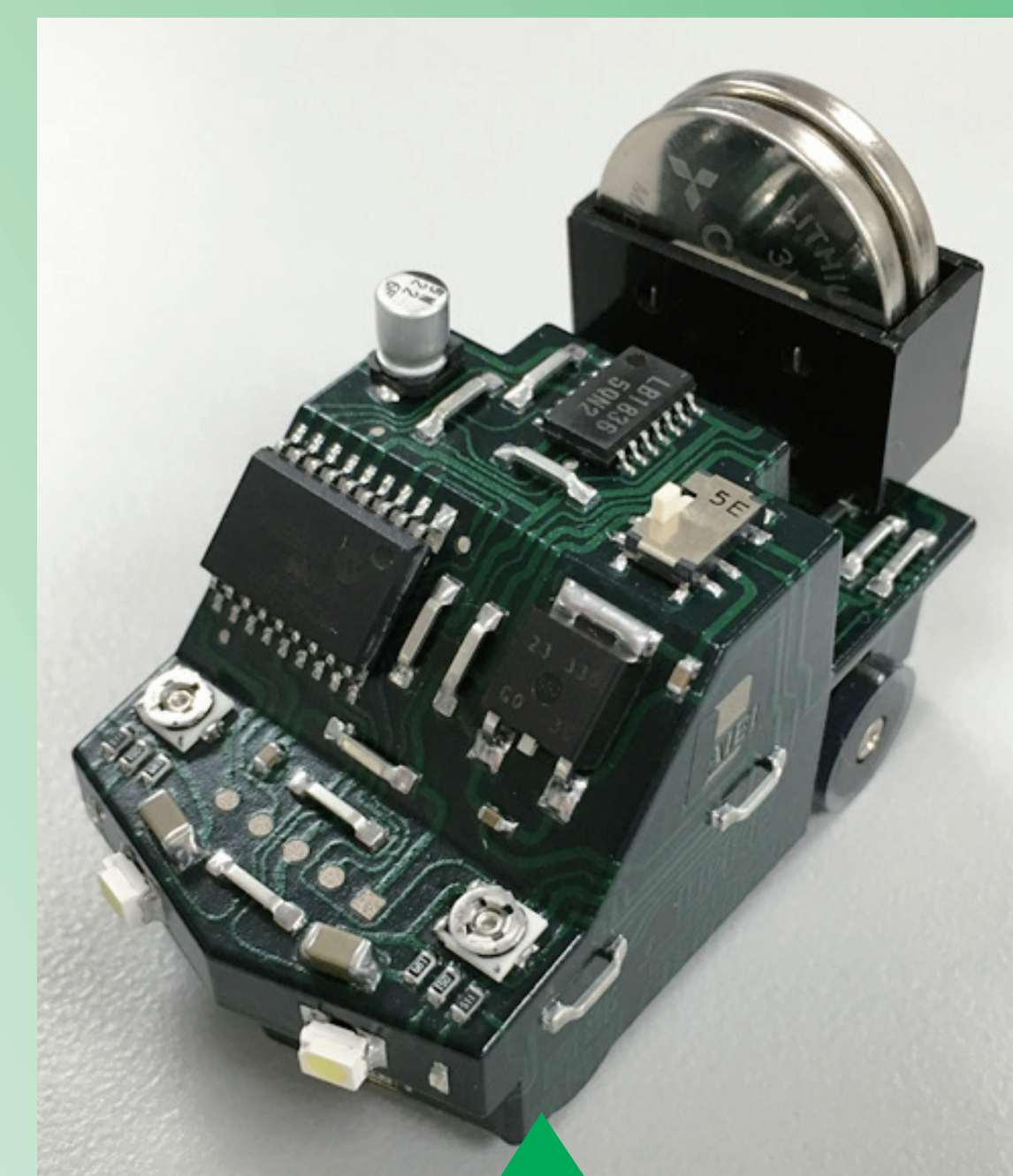


成型樹脂
Molding

回路形成 Patterning
+
銅めっき Copper plating

SR塗布
Resist coating

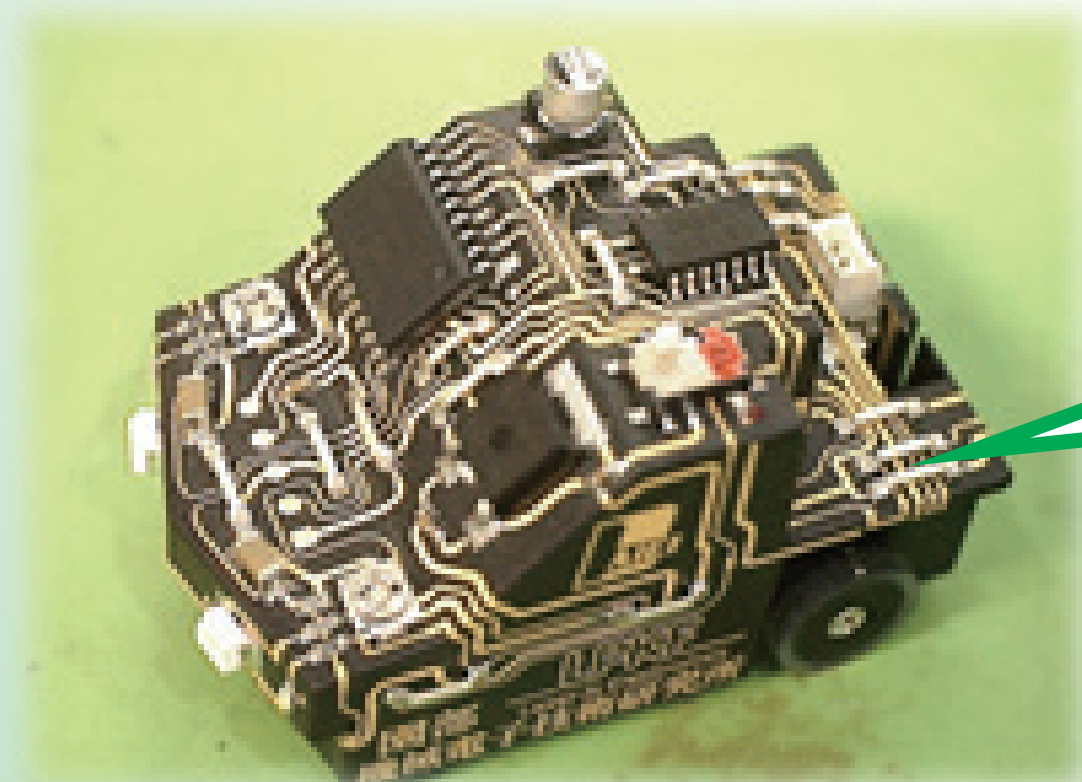
レーザー開口 Leaser trimming
+
金めっき E' less Ni/Au Plating



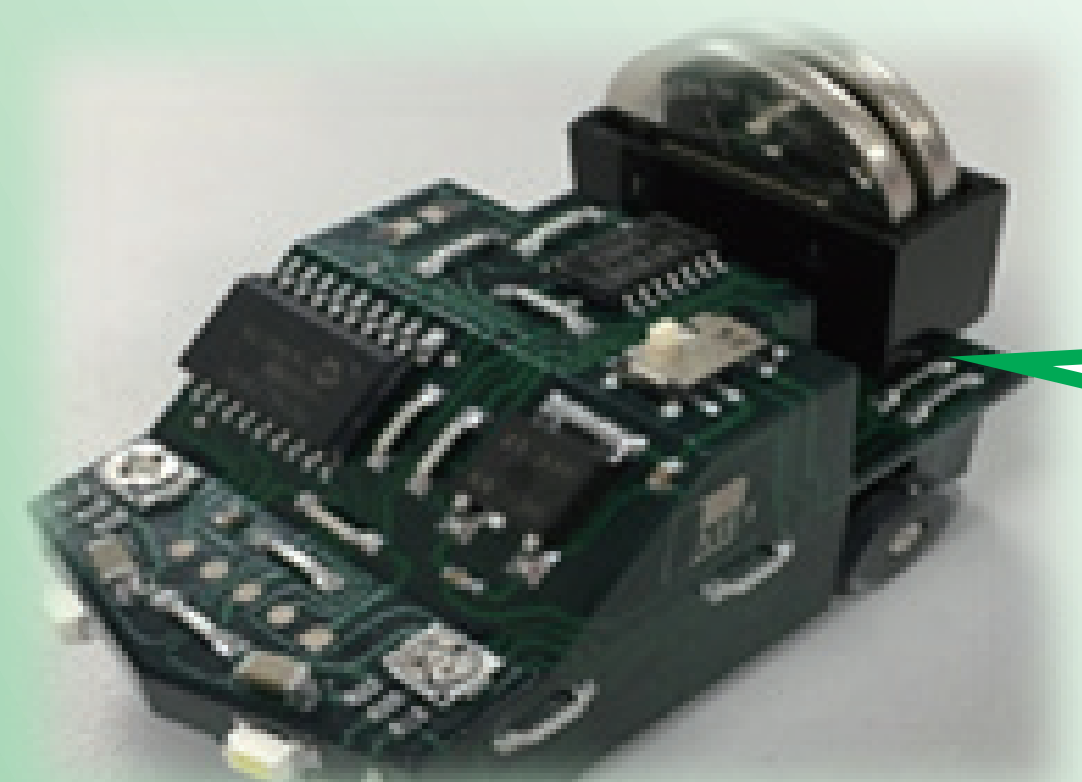
部品実装
Device mounting

● ソルダーレジストの役割 Roles of Solder resist

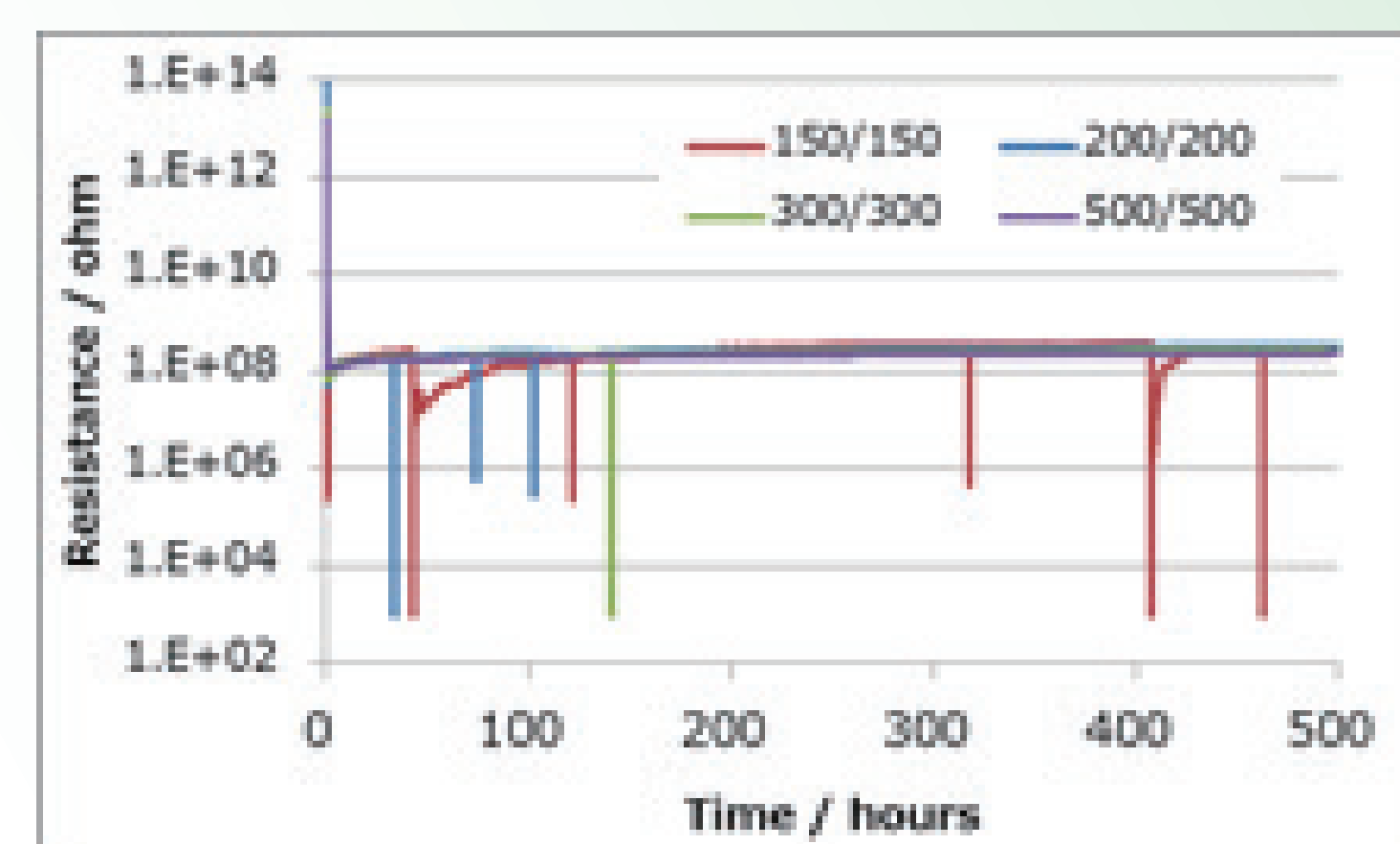
実装時の流れ防止
Prevention of solder outflow



金めっき削減によるコストダウン
Cost reduction by reducing gold plating area

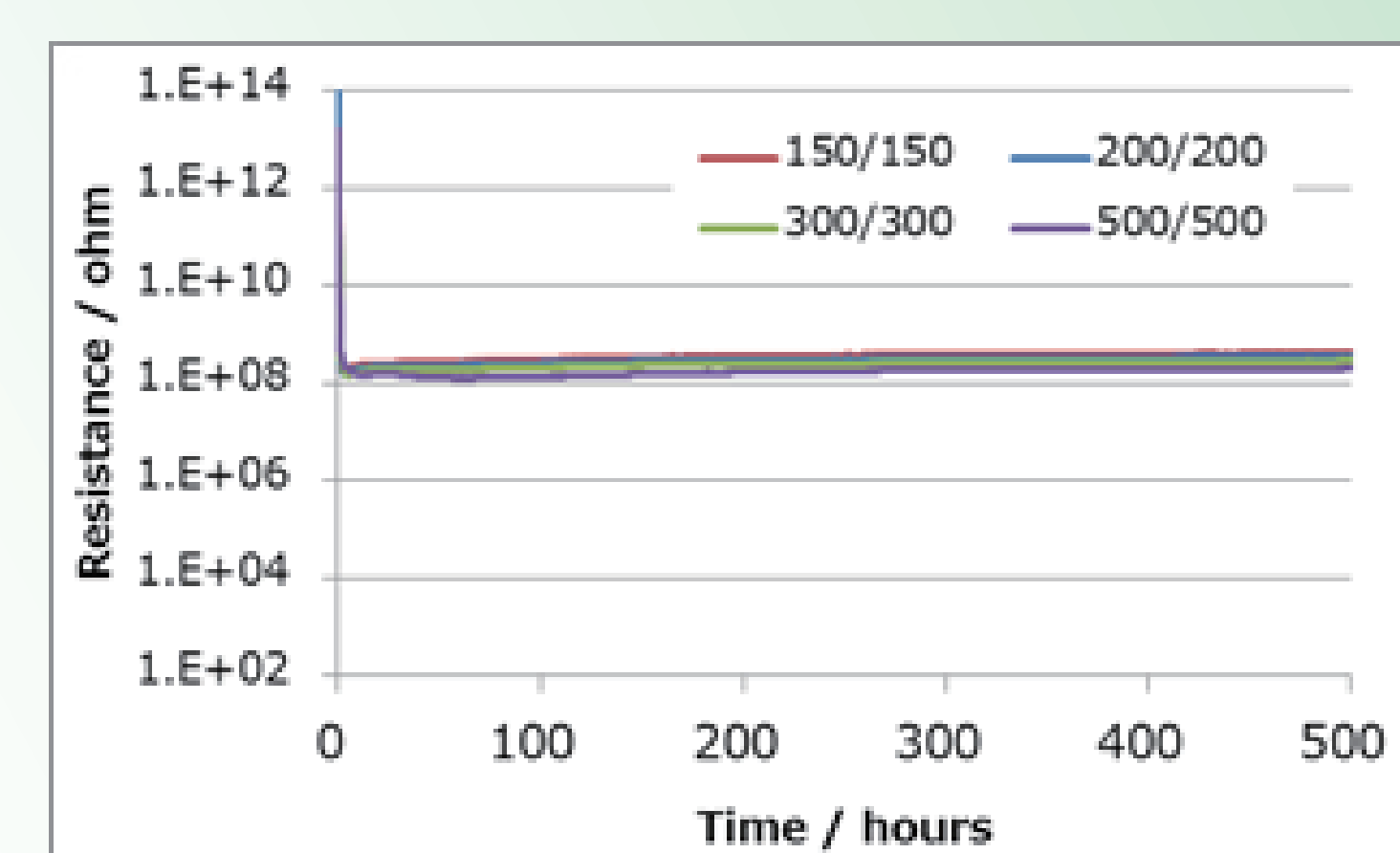


高絶縁信頼性
High insulation reliability



電気特性(85deg.C/85%RH/DC30V 基材:PA)
L/S=150/150 , 200/200 , 300/300 , 500/500 um

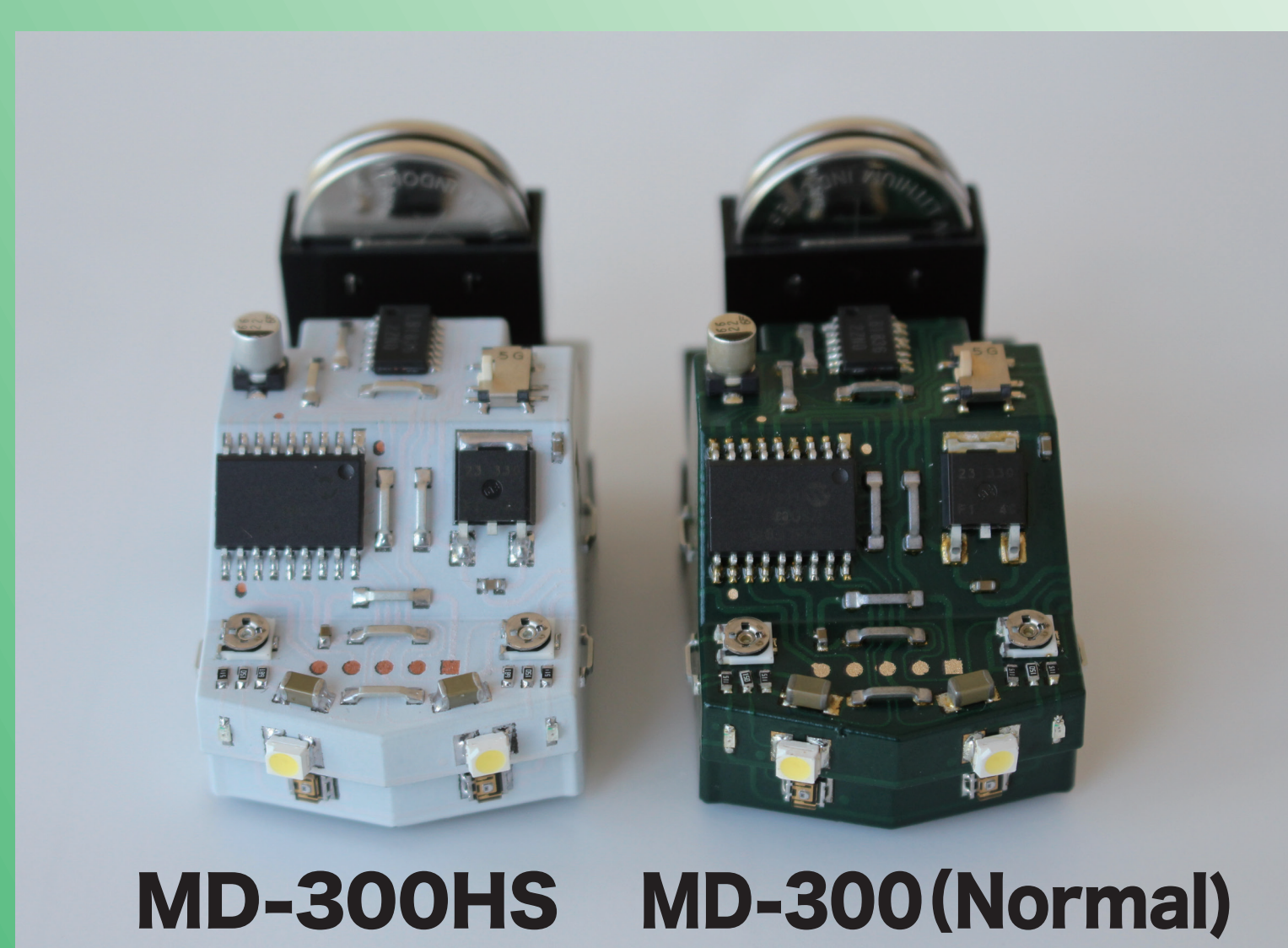
ソルダーレジストが
あれば
After coating
Solder resist



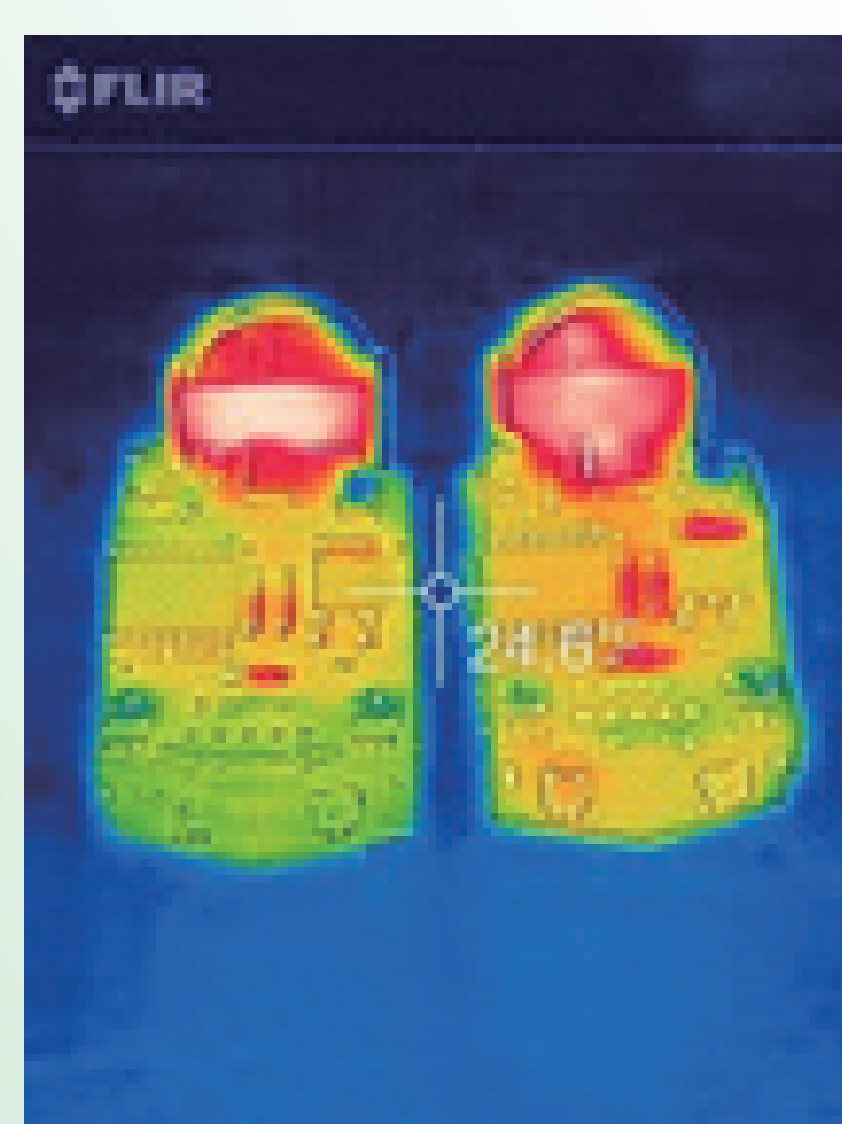
MD-300 HS Series

● 放熱仕様のレジストもご用意しております。

Solder resist for heat dissipation is newly released to 3D-MID application.



MD-300HS MD-300(Normal)



Effect of heat dissipation
(Approx. 10°C down)



TAIYO INK MFG. CO., LTD.